

2.5 Amp. Glass Passivated Bridge Rectifier

<p>Dimensions in mm.</p> <p>Plastic Case</p>	<p>Voltage 50 to 1000 V.</p> <p>Current 2.5 A.</p>
<p>• Mounting Instructions</p> <ul style="list-style-type: none"> • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm. 	<ul style="list-style-type: none"> • Glass Passivated Junction Chips. • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • The plastic material carries U/L recognition 94 V-O.

Maximum Ratings, according to IEC publication No. 134

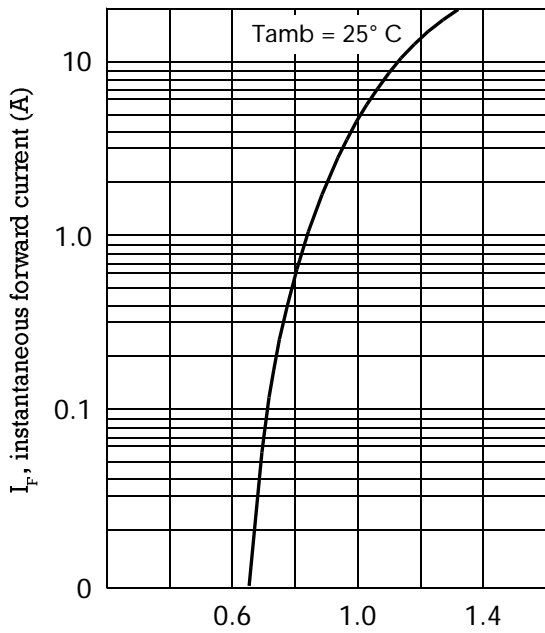
		FBI2.5A 4S1	FBI2.5B 4S1	FBI2.5D 4S1	FBI2.5G 4S1	FBI2.5J 4S1	FBI2.5K 4S1	FBI2.5M 4S1
V_{RRM}	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V_{RMS}	Maximum RMS voltage (V)	35	70	140	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	4.5 A at 65 °C 2.5 A at 25 °C						
I_{FSM}	8.3 ms. peak forward surge current (Jedec Method)	100 A						
I^2t	Rating for fusing ($t < 8.3$ ms.)	15 A ² sec						
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	1500 V						
T_j	Operating temperature range	– 55 to + 150 °C						
T_{stg}	Storage temperature range	– 55 to +150 °C						

Electrical Characteristics at Tamb = 25 °C

V_F	Max. forward voltage drop per element at $I_F = 2.5$ A	1.0V
I_R	Max. reverse current per element at V_{RRM}	5 μ A
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	12 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	40 °C/W

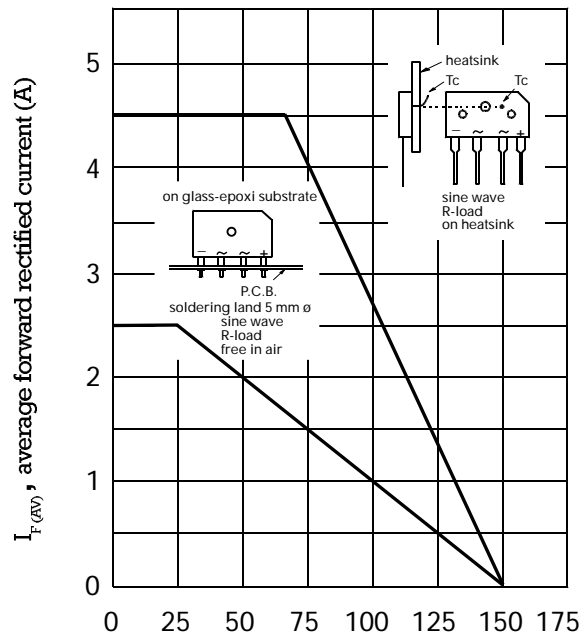
Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



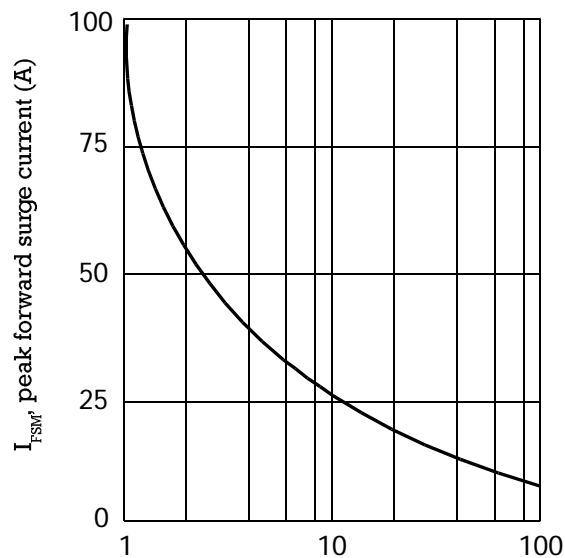
V_F , instantaneous forward voltage (V)

FORWARD CURRENT DERATING CURVE



T_{amb} , ambient temperature ($^{\circ}C$)

MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



Number of cycles at 60 Hz.